# Deciding Upon Readout Option for MaDPhoX

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### Comparing Readout Chips

Before irradiation it is simple:

- noise characteristics of chips
- 🔒 digital vs. analog readout



#### Performance after Irradiation

- Silicon damage is the primary concern
  - Some effects are local and impact only part of a strip, others impact the entire strip
- Some readout chips may receive significant radiation doses



## Radiation Effects in Silicon

- Increased interstrip capacitance
  - before: 1.2 pf/cm
  - @2E14 NEQ: 1.6 pf/cm (looking for 1E15)
- Trapping decreases charge collection
  - 🔒 before: no charge loss
  - @1E15 NEQ: ~20% loss per 100um drift
- Charge loss from underdepletion
  - before: fully depleted
  - After: covered in detail in previous talk.



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### Radiation Effects in Readout Chip



## Simulation

Changes to org.lcsim

- New readout chip BasicReadoutChip
  - thresholds as multiples of RMS noise: easy to simulate optimized readout
  - simulates generic ADC via two settable parameters:
    - hbits (number of bits resolution)
    - dynamic\_range (in fC)
  - binary readout (1 bit) is handled as a special case
- Change to CDFSiSim to simulate charge trapping
  - Can set fraction of charge loss per 100 microns drift
  - Depth dependent trapping is fully simulated

# Suggested Test Points

#### Before irradiation

- Silicon: 1.2 pf/cm, full charge collection
- ♣ ABCD3TA: 600+65\*C e- ENC
- APV25: 400+60\*C e- ENC (deconvolution mode)
- Irradiated silicon @1E15 NEQ, fully depleted
  - Silicon: 1.6 pf/cm, 20% / 100um drift charge trapping
  - ABCD3TA: 600+65\*C e- ENC
  - APV25: 400+60\*C e- ENC (deconvolution mode)
- Irradiated silicon @1E15 NEQ, fully depleted, irradiated chip @2E14
  - Silicon: 1.6 pf/cm, 20% / 100um drift charge trapping
  - ♣ ABCD3TA: 1100+65\*C e- ENC
  - APV25: 400+60\*C e- ENC (deconvolution mode)

# Summary

By testing a few cases we can get an idea where we stand.

- The code is there. The amount of new code is very small so I don't believe there will be a long debugging cycle.
- Once we have checked these scenarios, we can decide how hard we need to look at these issues.
- Beyond these, we should probably look at what happens with thinner silicon.
- I will be in touch with Matt to get him up and running.